June, 2001



(SCM6008-GL)



# Technical Specification for Optical Transceiver Module

# SCM6008-GL

155.52Mbps	622.08Mbps	other 2488.32Mbps	
Short Haul Intermediate Reach	Long Haul Long Reach	other	
Single 5.0 V	Single 3.3 V	other	
1.3 µm	1.55 μm	other	
Transmitter	Receiver	Transceiver	
	(	( <b>1</b> 2R / <b>1</b> 3R )	
Applicable Part Numbers	: SCM6008-GL-ZN, SCM6008	B-GL-CN, SCM6008-GL-DN	
•	SUMITOMO ELEC	TRIC	
•	OOMITOIVIO EEEO	11110	
Sumitomo Electric reserves the	right to make changes in this	specification without prior notice.	
			_
#Safety Precaution Symbols This persons or damage to properties for appropriate us with these symbols before reading this specification.	se of the product. The symbols and	symbols to prevent possible injury to operator or othe definitions are as shown below. Be sure to be fami	
↑ Warning Wrong operation withou	t following this instruction may lead	to human death or serious injury.	
	t following this instruction may lead	to human injury or property damage.	
Example of picture symbols indicates prohi	bition of actions. Action details are	explained thereafter.	
indicates comp	oulsory actions or instructions. Action	n details are explained thereafter.	

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#### 1. General

Features and applications of SCM6008-GL are listed below.

Features

\* Multi Bit Rate Operation 155Mbps ~ 2.5Gbps

\* Power Supply Voltage Single +3.3V

\* Compact Package Size 49.0 X 13.59 X 9.8 mm (max.)

\* Electrical Interface LVPECL for DATA and LVTTL for Signal Detect and Laser Disable

\* Fiber Coupled Power -5 ~ 0dBm into SMF

\* Input Power Range 0 ~ -18dBm

\* Monitor Functions Laser Bias Monitor, Rear Facet Monitor

\* Laser Disable Function

\* Signal Detect (SD) Function

\* Connector Interface LC Duplex Connector

**Applications** 

\*Telecommunications

\*Data communications

>High Speed Rack-to-Rack Data Links

> SONET/IR, SDH/SH Application

> ATM Application

> Shelf-to-Shelf Multi Bit Rate Application

> Subscriber Loop

> Metropolitan Area Network

# 2. Block Diagram

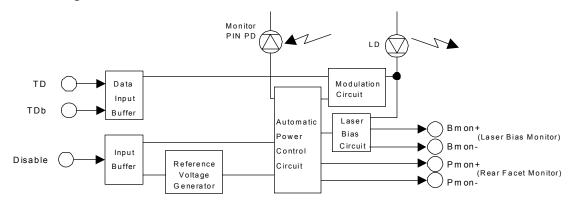


Figure 1. Block Diagram (Transmitter)

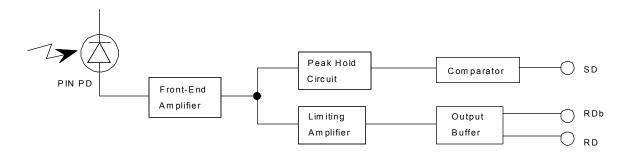


Figure 2. Block Diagram (Receiver)

# **∧** Caution

 $\gamma$  Do not disassemble this product. Otherwise, failure, electrical shock, overheating or fire may occur.

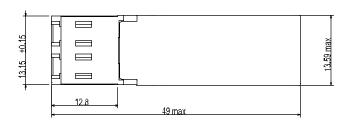
Handle the lead pins carefully. Use assisting tools or prospective aids as required. A lead pin may injure skin or human body.

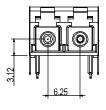
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# 3. Package Dimension

\*All dimensions are in mm.

\*Receptacle portion (approx. 12.8mm from front) is metalized.





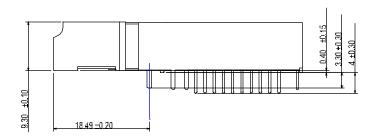




Figure 3. Outline Dimensions (SCM6008-GL-ZN)

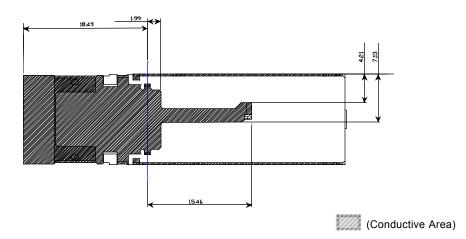
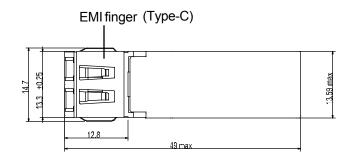
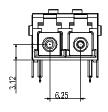
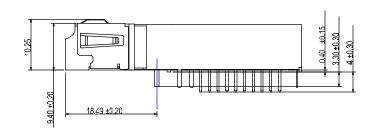


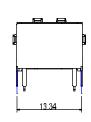
Figure 4. Bottom Side (SCM6008-GL-ZN)

Specification : TS-S00D032D June, 2001









Type-C EMI finger is an option for transceivers to be used on the card-edge with the receptacle protruding through a panel opening. It has fingers on three sides to make electrical contact with the sides of the bezel opening for grounding purpose.

Figure 5. Outline Dimensions (SCM6008-GL-CN)

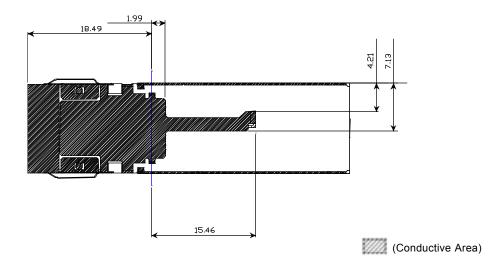
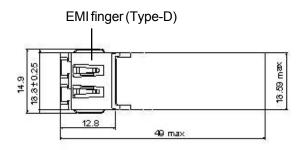
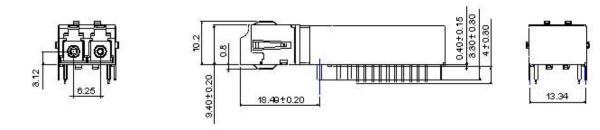


Figure 6. Bottom Side (SCM6008-GL-CN)

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Type-D EMI finger is an option for transceivers to be used on the card-edge with the receptacle protruding through a panel opening. It has fingers on four sides to make electrical contact with the sides of the bezel opening for grounding purpose.

Figure 7. Outline Dimensions (SCM6008-GL-DN)

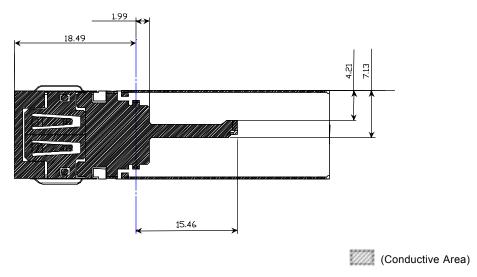
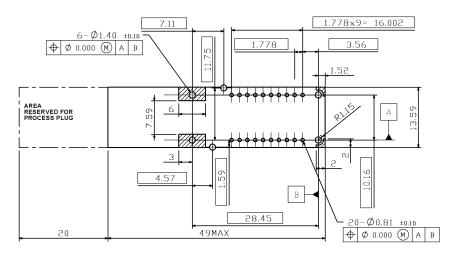


Figure 8. Bottom Side (SCM6008-GL-DN)

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Keep-out areas reserved for housing standoffs

Figure 9. Recommended Footprint

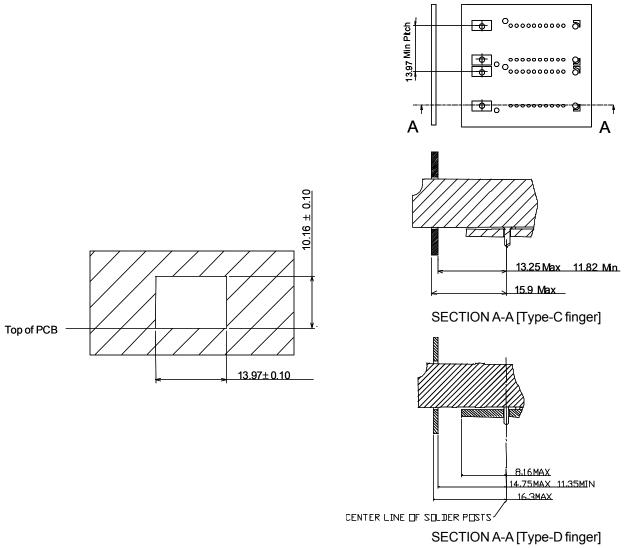


Figure 10. Recommended Bezel Design for Systems Using SFF Transceivers

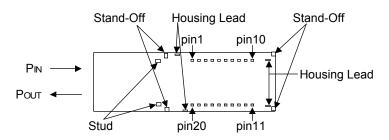
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# 4. Pin Assignment

No.	Symbol	I/O/P	Level	Description
1	VpdR	Р	+3.3V DC	DC Bias Supply for Receiver PIN-PD.
2	VeeR	Р	GND	Power Supply (-) for Receiver.
3	VeeR	Р	GND	Power Supply (-) for Receiver.
4	NC			No User Connection.
5	NC			No User Connection.
6	VeeR	Р	GND	Power Supply (-) for Receiver.
7	VccR	Р	+3.3V DC	Power Supply (+) for Receiver.
8	SD	0	LVTTL	Signal Detect. High level indicates presence of optical input signal (Active High).
9	RDb	0	LVPECL	Inverted Receiver Output Data. No internal terminations are provided.
10	RD	0	LVPECL	Non-Inverted Receiver Output Data. No internal terminations are provided.
11	VccT	Р	+3.3V DC	Power Supply (+) for Transmitter.
12	VeeT	Р	GND	Power Supply (-) for Transmitter.
13	Tdis	1	LVTTL/LVCMOS	<b>Transmitter Disable (Active High).</b> Defaults to logic 0 (enable TX) when left open.
14	TD	-	LVPECL	Non-Inverted Transmitter Input Data. Self biased and internally terminated.
15	TDb	I	LVPECL	Inverted Transmitter Input Data. Self biased and internally terminated.
16	VeeT	Р	GND	Power Supply (-) for Transmitter.
17	Bmon-	0	Analog Voltage	LD Bias Current Monitor. Voltage difference between pins 17 and 18 is proportional
18	Bmon+	0		to the laser bias current.
19	Pmon-	0	Analog Voltage	Rear Facet Monitor. Transmitter output power can be monitored, in terms of rear
20	Pmon+	0		facet monitor PD current, by measuring voltage difference between pins 19 and 20.

#### Notes:

- 1. I/O/P stand for signal input, signal output, and DC power/bias supply, respectively.
- 2. Refer to figure 14 for details of Bmon and Pmon outputs.



- \* Mounting Studs are provided for mechanical support to the circuit board.
  - It is recommended that the holes in the circuit board be connected to frame ground.
- \* Housing Leads are internally connected to VeeR.
- \* Stand-Offs provide gap between the circuit board and the module to help escape residual water after aqueous wash.

Figure 11. Bottom View

# 5. Absolute Maximum Ratings

Parar	neter	Symbol	Min.	Тур.	Max.	Unit	Note
Storage Case Temperature		Ts	-40	-	85	°C	1
Operating Case T	emperature	Tc	-5	-	70	°C	1
Supply Voltage		Vcc	0.0	-	4.0	V	
PIN-PD Bias Volta	age	VpdR	-	-	7.0	V	
Input Voltage		Vi	0.0	-	Vcc+0.5	V	2
Lead Soldering	Temperature				260	°C	3
	Time				10	sec.	3

#### Notes

- 1. No condensation allowed.
- 2. TD, TDb, Tdis
- 3. Measured on lead pin at 2mm (0.079in.) off the package bottom.

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Use the product with the rated voltage described in the specification. If the voltage exceeds the maximum rating, overheating or fire may occur.

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7)

Do not store the product in the area where temperature exceeds the maximum rating, where there is too much moisture or dampness, where there is acid gas or corrosive gas, or other extreme conditions. Otherwise, failure, overheating or fire may occur.

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#### 6. Electrical Interface

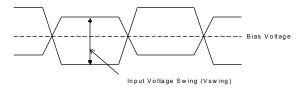
(Unless otherwise specified, Vcc = 3.135 to 3.465 V and all operating temperature shall apply.)

#### 6-1. Transmitter side

Parameter		Symbol	Min.	Тур.	Max.	Unit	Note
Supply Voltage		Vcc	3.135	3.30	3.465	V	
Supply Current		Idtx		95	200	mA	1, 2
Differential Input Voltage S	wing (TD,TDb)	Vin	0.4		2.00	Vp-p	3
Input Impedance		Rin	75	100	125	Ω	4
Signal Input Rise/Fall Time	<b>!</b>	tr / tf			120	psec	5
Tdis Input Voltage	High	Vdi	2.0		Vcc	V	6
	Low	Vei	0.0		0.8	V	0
Turn-on Time		ton			3	ms	7
Turn-off Time		toff			10	μs	7
LD Bias Monitor Voltage		Vbm	5		700	mV	1, 8
Rear Facet Monitor Voltage	Э	Vrfm	10		200	mV	1, 8

#### Notes

- 1. 50% duty cycle data.
- 2. 2488.32Mbps
- 3. Refer to Figure 12.
- 4. Measured between TD and TDb
- 5. 20 ~ 80%
- LVTTL input. Refer to Section 8, "Relation between Disable Input Voltage and Optical Output Power", for detail.
- 7. Refer to Figure 13.
- 8. The Laser Bias Monitor Current and Rear Facet Monitor Current are calculated as ratios between the corresponding voltages and current sensing resistors,  $200\Omega$ , as shown in the Figure 14.



Differential Input Voltage Swing (Vin) = 2 X Vswing

Figure 12. Definition of Differential Input Voltage Swing

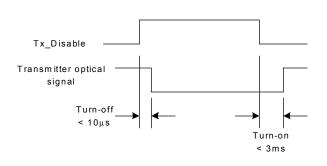
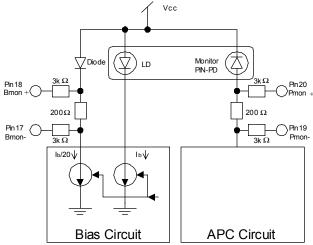


Figure 13. Definition of Turn-on / Turn-off Time



Resistance values are typical.

Figure 14. Bmon / Pmon Circuit Detail

#### 6-2. Receiver side

Paran	neter	Symbol	Min.	Тур.	Max.	Unit	Note
Supply Voltage		Vcc	3.135	3.30	3.465	V	
Supply Current		Idrx		80	130	mA	1
PIN-PD Bias Voltage		VpdR	2.40	3.3	5.25	V	
RD and RDb	High	Vdoh	Vcc-1.10		Vcc-0.65	V	2
Output Voltage	Low	Vdol	Vcc-1.80		Vcc-1.30	1	
SD	High	Vsoh	2.40		Vcc	V	
Output Voltage	Low	Vsol	0.0		0.5	1	
Data Rise / Fall Time		tr / tf		140 / 120		psec	3
SD Assert Time		ta	2.3		100	μsec	4
SD Deassert Time		td	2.3		350	μsec	4

#### Notes

- 1. Output current is not included.
- 2. Output load resistance RI=50 $\Omega$  to Vcc-2V for RD, RDb.
- 3. 20~80%
- 4. 2488.32Mbps, PRBS 2^23-1, NRZ

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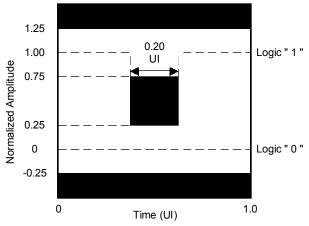
# 7. Optical Interface

(Unless otherwise specified, Vcc = 3.135 to 3.465 V and all operating temperature shall apply.)

#### 7-1. Transmitter side

Parameter	Symbol	Min.	Тур.	Max.	Unit	Note
Average Output Power	Po	-5.0		0.0	dBm	1
Extinction Ratio	Er	8.2			dB	1
Center Wavelength	λς	1260		1360	nm	
Spectral Width (-20dB Width)	Δλ			1	nm	
Side Mode Suppression Ratio	Sr	30			dB	
Eye Mask for Optical Output	Comp	Compliant with Bellcore GR-253 CORE and ITU G957				

Note 1. Measured at 2488.32Mbps PRBS2^23-1, 50% duty cycle, NRZ.



# Relation between Input Signal and Optical Output Signal

Input Signal		Optical Output Signal
TD	TDb	
High	Low	ON (High)
Low	High	OFF (Low)
High	High	Undefined
Low	Low	Undefined

Figure 15. Optical Pulse Mask with Fourth Order

Bessel-Thomson Filter Specified in ITU-T G.957

# **△** Warning

Do not look at the laser beam projection area (e.g. end of optical connector) with naked eyes or through optical equipment while the power is supplied to this product. Otherwise, your eyes may be injured.

#### 7-2. Receiver side

Parameter	Symbol	min.	Тур.	Max.	Unit	Note
Center Wavelength	-	1260		1360	nm	
PD Responsivity		0.7		1.1	A/W	
Minimum Sensitivity	Pmin			-18.0	dBm	1, 2
Overload	Pmax	0			dBm	1, 2
SD Assert Level	Pa		-22		dBm	2
SD Deassert Level	Pd		-25		dBm	
SD Hysteresis	Phys	0.5	3		dB	
Reflectance	REFr		-14		dB	

Note 1. BER=10^-10

2. Measured at 2488.32Mbps, PRBS 2^23-1, NRZ

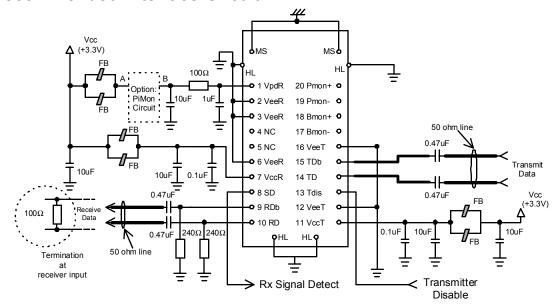
# 8. Relation between Disable Input Voltage and Optical Output Power

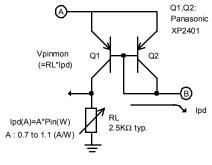
Disable Input Voltage	Optical Output Power		
"L"(0 ~ 0.8V)	Enabled		
"H"(2.0V ~ Vcc)	Disabled (<-45dBm)		

\*Note: Enabled for no Disable input (Pin 13 open)

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### 9. Recommended Interface Circuit





PiMon Circuit

FB:BLM11HA601SG(Murata)

MS: Mounting Stud

HL: Housing Lead

#### Notes:

- (1) Components on RD/RDb lines,240 $\Omega$  and 0.47uF, should be placed as close as possible to module pins.
- (2) Coupling capacitors on RD/RDb and TD/TDb lines,0.47uF, can be as low as 0.1uF if multi bit rate operation is not needed.
- (3) 0.1uF capacitors on VccR/VccT lines should be as close as possible to module pins.
- (4)  $50\Omega$  line pattern and component placements on RD/RDb and TD/TDb lines should be
- symmetrical for better impedance matching.
- (5) HL is internally connected to VeeR.(6) VeeR and VeeT are not internally connected to each other.



Figure 16. Recommended Interface Circuit

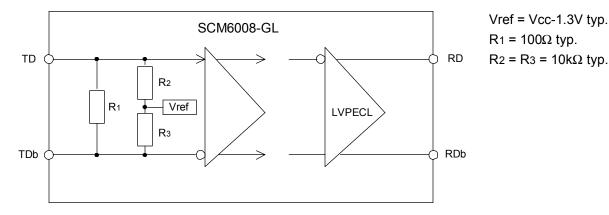


Figure 17. Electrical Data Interface

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# 10. Reliability Test Program

GR-468-CORE Issue 1, December 1998 Laser Module

HEADING	TEST	REFERENCE	CONDITIONS	SAM	PLIN	G
				LTPD	SS	С
	Mechanical	MIL-STD-883	5 times/axis			
	Shock	Method 2002	1,500G, 0.5ms	20	11	0
Mechanical	Vibration	MIL-STD-883	Cond. A 20G, 20-2,000	20	11	0
Integrity		Method 2007	Hz, 4min/cy, 4cy/axis			
	Thermal Shock	MIL-STD-883	Delta T=100°C	20	11	0
		Method 1011	0°C to 100°C			
	Solderability	MIL-STD-883	(steam aging not	20	11	0
		Method 2003	required)			
	Accel. Aging	(R)-4-53 Section	85°C; rated power			-
	(High Temp.)	5.18	1,000 hrs. for pass/fail	-	25	
			2,000, 5,000 hrs. for info.		10	
Endurance	Low Temp.	-	min. storage T	20	11	0
	Storage		1,000 hrs. for pass/fail			
			2,000 hrs. for info.			
	Temperature	Section 5.20	-40°C to +85°C			
	Cycling		500 for pass/fail	20	11	0
			1,000 for info.	-	11	-
	Damp Heat	MIL-STD-202	85°C/85%RH 1,000hrs.	20	11	0
		Method 103 or				
		IEC-60068-2-3				
	Cyc. Moist. Res.	Sec. 5.23	-	20	11	0
Special Tests	Internal	MIL-STD-883	Max. 5,000ppm water	20	11	0
	Moisture	Method 1018	vapour			
	ESD Threshold	Section 5.22		-	6	-

SS: Sample Size

C: Maximum number of failure allowed to pass the test.

# 11. Laser Safety

This product uses a semiconductor laser system and is a laser class 1 product acceptable. FDA, complies with 21CFR 1040. 10 and 1040.11. Also this product is a laser class 1 product acceptable. IEC 60825-1.

Class 1 Laser Product

# **⚠** Caution

 $\bigcirc$ 

If this product is used under conditions not recommended in the specification or this product is used with unauthorized revision, classification for laser product safety standard is invalid. Classify the product again at your responsibility and take appropriate actions.

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#### 12. Other Precaution

Under such a strong vibration environment as in automobile, the performance and reliability are not guaranteed. This module must be handled, used and disposed of according to your company's safe working practice.

# ⚠ Warning



Be sure to carry out correct soldering for connection to peripheral circuits in order to prevent contact failure or short-circuit. Otherwise, a strong laser beam may cause eye injury, overheating or fire.

Do not put this product or components of this product into your mouth. This product contaions material harmful to health.

# 



Be sure to turn the power off when you touch this product connected to the printed circuit boards. Otherwise, electric shock may occur.

Dispose this product or equipment including this product properly as an industrial waste according to the regulations.

# 13. Ordering Information

Ordering Number	Connector Type	EMI Shield Finger Option	Operating Case Temperature
SCM6008-GL-ZN	LC Duplex Receptacle,Metallized	Without Finger	
SCM6008-GL-CN	LC Duplex Receptacle,Metallized	With Type-C Finger	-5°C ~ 70°C
SCM6008-GL-DN	LC Duplex Receptacle,Metallized	With Type-D Finger	

#### 14. For More Information

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